Surface Mount Superfast Recovery Rectifier

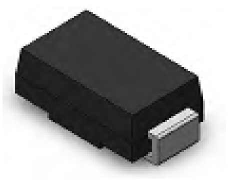
FEATURES:

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

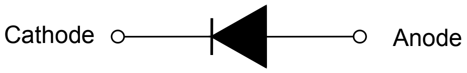
Marking

Type number	Marking code
ES1A	ES1A
ES1B	ES1B
ES1C	ES1C
ES1D	ES1D
ES1E	ES1E
ES1G	ES1G
ES1J	ES1J

Circuit Diagram & Pin Configuration:



SMA/DO-214AC



Absolute Maximum Ratings and Characteristics

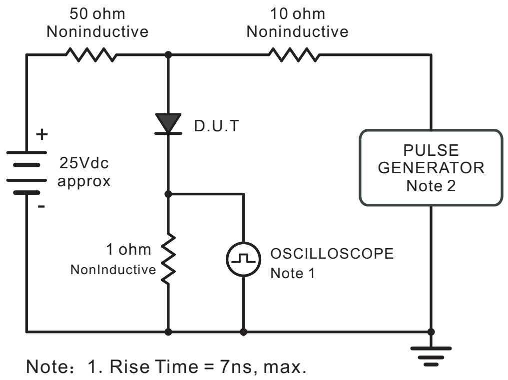
Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbols	ES1A	ES1B	ES1C	ES1D	ES1E	ES1G	ES1J	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	30							A
Maximum Forward Voltage at 1 A	V_F	1				1.25		1.70	V
Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta =125 °C	I_R	5 100							μA
Typical Junction Capacitance at V_R=4V, f=1MHz	C_j	15							pF
Maximum Reverse Recovery Time (1)	t_{rr}	35							ns
Typical Thermal Resistance (2)	$R_{\theta JA}$	75							°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							°C

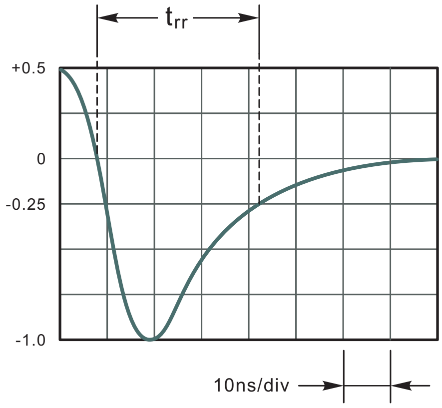
(1) Measured with I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A.

(2) P.C.B. mounted with 1.0 X 1.0" (2.54 X 2.54 cm) copper pad areas.

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm,22pF.
2. Ries Time =10ns, max.
Source Impedance = 50 ohms.



Set time Base for 10ns/div

Fig.2 Maximum Average Forward Current Rating

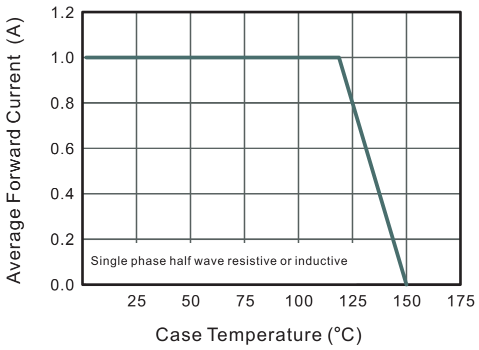


Fig.3 Typical Reverse Characteristics

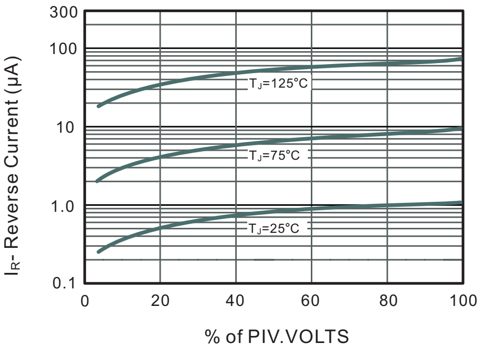


Fig.4 Typical Forward Characteristics

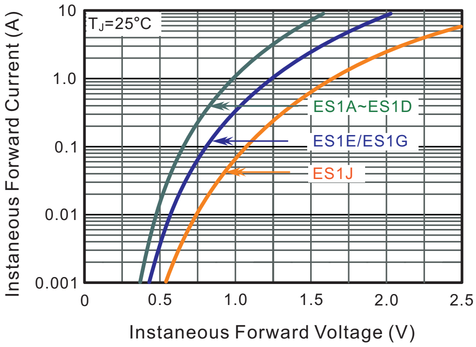


Fig.5 Typical Junction Capacitance

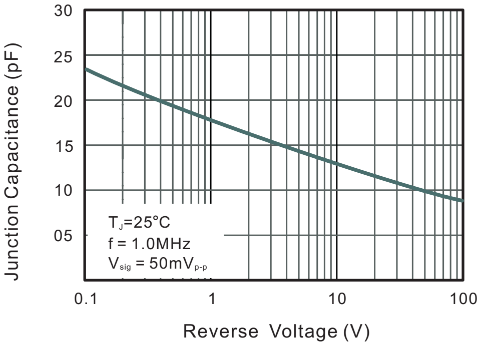
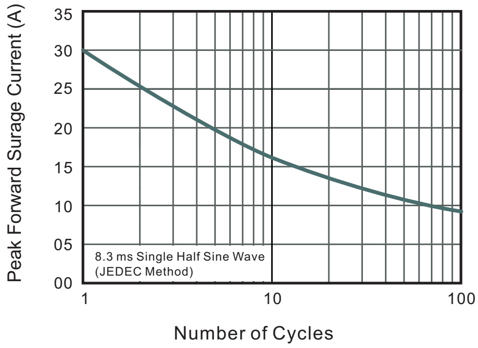
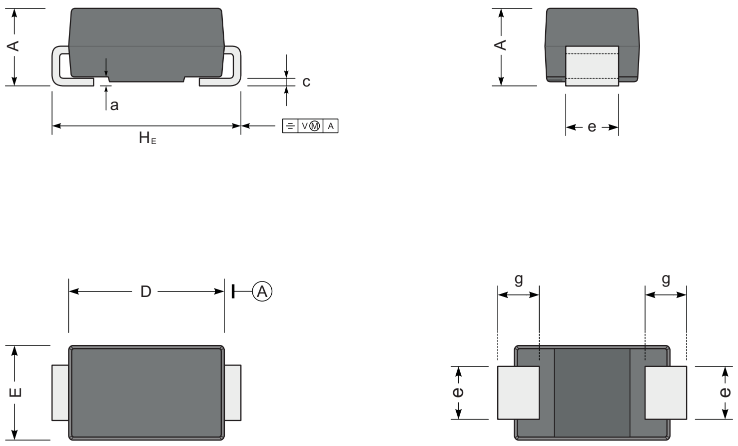


Fig.6 Maximum Non-Repetitive Peak Forward Surage Current



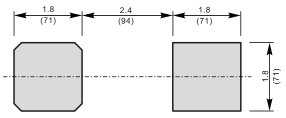
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads **SMA/DO-214AC**



UNIT		A	D	E	HE	c	e	g	a
mm	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.3
	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	
mil	max	87	181	106	205	12	63	59	12
	min	75	157	91	185	6	51	35	

The recommended mounting pad size



Unit : mm / (mil)

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